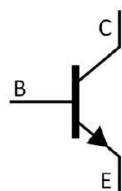


/ Descriptions

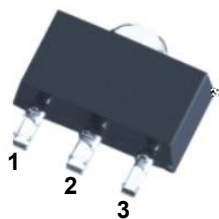
/ Features

/ Applications

/ Equivalent Circuit



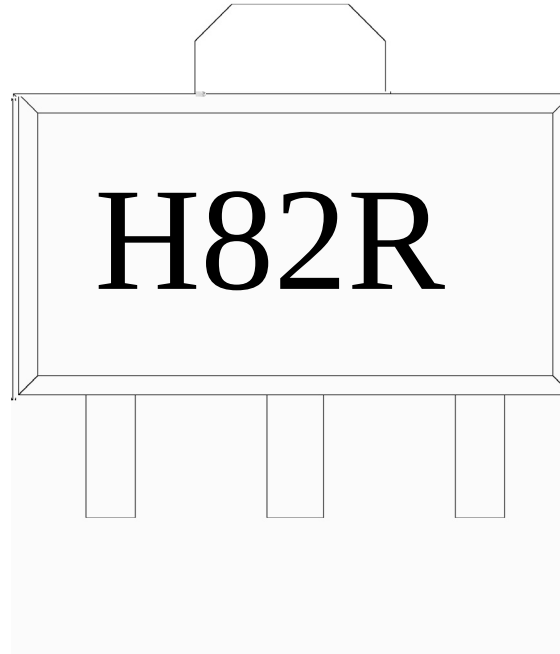
/ Pinning



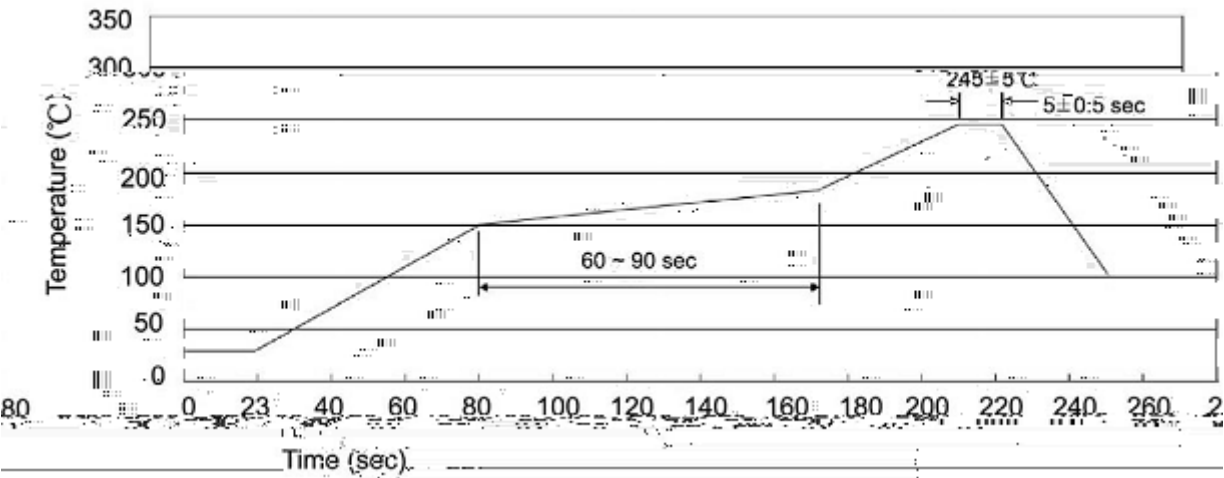
/ Marking

	**	**	**	**

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ Notices